Method for Producing Chip Stacks as well as

a Carrier for Executing the Method

Abstract

The invention relates to a method for producing chip stacks (31) with the following method sequence:

- applying an especially dielectric and/or photostructurable base layer (20) to one carrier side (15) of a carrier (10) which on its carrier side (15) is provided with an adhesively acting adhesion zone (14) and a less adhesively acting support zone (11), the base layer (20) being applied largely over the entire surface at least to the support zone (11),
- building up the chip stacks (31) on the base layer (20),
- potting of the chip stacks (31),
- detaching the carrier (10) from the base layer (20).

Moreover the invention relates to a carrier for executing this method.

Figure 11H5